

Module reception v1.0

Transfer ID :

<i>Action</i>	<i>remark</i>	<i>o.k</i>
Transfer accepted		
IDs Checked ¹⁾		
Modules still in place in box ²⁾		
No free pieces inside boxes		
Rough inspection of modules ^{a)}		
microscope inspection ^{a) b)}		
Test bonds removed ³⁾		
Rbias if no bckpl. bonds ^{c)}		
damaged module set faulty		
Failure report posted ^{d)}		
Module IDs 2D barcode? ⁴⁾		
No missing NAIS connector		
No sticker left ⁵⁾		

Date Initials

Additional actions if not o.k.

- 1) inform sender
- 2) take pictures, do an ARC test if module dubious (touched bonds) and contact sender (old design box? If yes, top foam installed?)
- 3) Remove the test bonds
- 4) change the module ID well before the assembly
- 5) on hybrid, 1D barcode on leg, other? remove it

Remarks:

- a) if module damaged, follow Manfred's procedure:
(<http://agenda.cern.ch/askArchive.php?base=agenda&categ=a056708&id=a056708s1t38/actionlist>)
- b) backplane bonds need special attention checking they are still ALL there and not loosing
- c) keep track of the value you measure; put a warning (mail to Manfred?) if too high (> 1 ohm?)
- d) to post a failure report (<http://cms.ct.infn.it/failures>, you need a login and a password, please ask Guido or Jean-Charles